MAZLxxxH Series

Silicon planar type

For surge absorption circuit

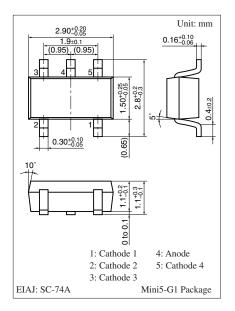
■ Features

- Four elements anode-common type
- Power dissipation P_D: 200 mW

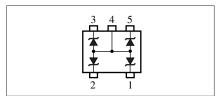
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Power dissipation *	P_{D}	200	mW
Junction temperature	T_{j}	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Note) *: P_D = 200 mW achieved with a printed circuit board.



Internal Connection



■ Common Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter	Symbol		Conditions	Mi	т Тур	Max	Unit
Zener voltage*	Vz	I_Z	Specified value —				V
Zener rise operating resistance	R _{ZK}	I_Z	Specified value	Refer to the list of the electrical characteristics			Ω
Zener operating resistance	R _Z	I_Z	Specified value	within par		Ω	
Reverse current	I_R	V _R	Specified value				μΑ

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Electrostatic breakdown voltage: ±10 kV

Test method: IEC1000-4-2 (C = 150 pF, R = 330 Ω , Contact discharge: 10 times)

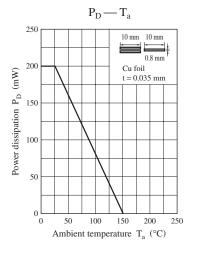
3. *: The temperature must be controlled 25°C for V_Z mesurement.

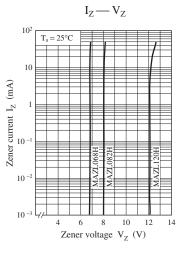
 V_Z value measured at other temperature must be adjusted to V_Z (25°C)

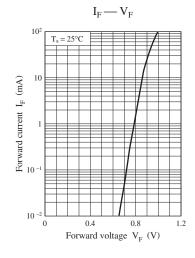
V_Z guaranted 20 ms after current flow.

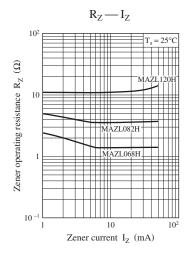
■ Electrical characteristics within part numbers $T_a = 25^{\circ}C \pm 3^{\circ}C$

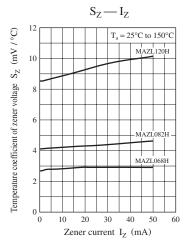
Part number	Zener voltage V _Z (V)			Reverse current		Zener operating resistance $R_Z(\Omega)$	Zener rise operating resistance $R_{ZK}(\Omega)$	Marking symbol	
	Min	Nom	Max	I _Z (mA)	Max	V _R (V)	$I_Z = 5 \text{ mA}$ Max	I _Z = 0.5 mA Max	
	IVIIII	INOIII	IVIAA	(1117)	IVIAA	(v)	IVIAA	IVIAX	
MAZL068H	6.4	6.8	7.2	5	0.1	4	30	60	6.8Z
MAZL082H	7.7	8.2	8.7	5	0.1	5	30	60	8.2Z
MAZL120H	11.4	12.0	12.7	5	0.05	9	30	80	12Z

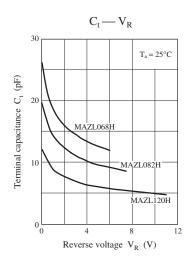












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